



## Message from the Editor

*Transactions of The Japan Institute of Electronics Packaging (Trans. JIEP*, English version) is a representative technical journal in electronics packaging (Jisso) technology. This is its eighth volume. *Trans. JIEP* aims to share the newest results and achievements on Jisso technology with engineers worldwide, including assembling, packaging, mounting, interconnection, thermal management, electromagnetic characteristics, and more.

In recent years, the use of various power electronics products in the car industry and wearable devices in healthcare and medical applications has increased significantly. This trend increases the importance of Jisso technology, and promotes its further progress. This year's volume contains 21 technical papers and one short note that were selected from 28 submitted manuscripts through a strict review process. These papers involve the latest results in various aspects of Jisso technology, and we are sure that they will provide much valuable and helpful information to all Jisso engineers. Although only a small number of papers in this volume are from overseas, we surely welcome the submission of high-quality overseas papers. We believe that *Trans. JIEP* is a good platform to publish your important and remarkable achievements, because since it was first published in 2008, it has established a solid reputation as a representative journal in the Jisso area. The deadline for manuscript submission for the next volume is expected to be the end of June, 2016.

Finally, as the editor-in-chief, I would like to express my sincere appreciation to all the authors for their great contributions to this volume. I would also like to thank all the reviewers for their precious time as well as providing useful feedback to the authors. Moreover, without the hard voluntary work of the editorial committee members and staffs, this volume would not be possible. I am especially thankful for the strong support of the vice-editor-in-chief, Dr. K. Hashimoto, Prof. J. Mizuno, and Dr. S. Yamamichi, as well as the editorial staff, Ms. T. Takahashi.

December 10, 2015

Jianqing Wang  
Editor-in-Chief

Transactions of The Japan Institute of Electronics Packaging  
Professor, Nagoya Institute of Technology, Japan

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